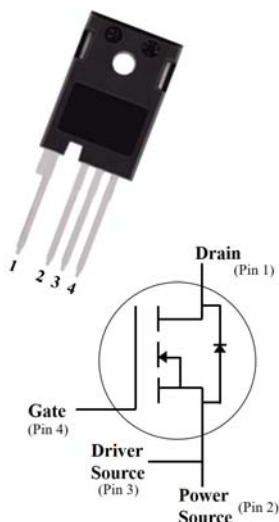


Silicon Carbide Power MOSFET (N-Channel Enhancement)

V_{DS}	1200V
I_D (25°C)	65A
$R_{DS(on)}$	36mΩ



Features

- High speed switching
- Essentially no switching losses
- Reduction of heat sink requirements
- Maximum working temperature at 175 °C
- High blocking voltage
- Fast Intrinsic diode with low recovery current
- High-frequency operation
- Halogen free, RoHS compliant

Typical Applications

Typical applications are in power factor correction (PFC), solar inverter, uninterruptible power supply, motor drives, photovoltaic inverter, electric car and charger.

Mechanical Data

- **Package:** TO-247-4L
- **Terminals:** Tin plated leads
- **Polarity:** As marked

■Maximum Ratings (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	VALUE	TEST CONDITIONS	NOTE
Device marking code			D212040NCFYG3M		
Drain source voltage @ T _j =25°C	$V_{DS,max}$	V	1200	$V_{GS}=0V, I_D=100\mu A$	
Gate source voltage @ T _j =25°C	$V_{GS,max}$	V	-8/+22	Absolute maximum values (AC f > 1Hz, duty cycle < 1%)	
Gate source voltage @ T _j =25°C	$V_{GS,op}$	V	-5/+18	Recommended operational values	
Continuous drain current @ T _c =25°C	I_D	A	65	$V_{GS}=18V, T_c=25^\circ C$	Fig.16
Continuous drain current @ T _c =100°C			32	$V_{GS}=18V, T_c=100^\circ C$	
Pulsed drain current	$I_{D(pulsed)}$	A	138	Pulse width t _p limited by T _{j,max} ⁽¹⁾	Fig.21
Power Dissipation	P_{TOT}	W	288	T _c =25°C, T _j = 175°C	Fig.15
Power Dissipation			76	T _c =100°C, T _j = 175°C	
Operating junction and Storage temperature range	T _j , T _{stg}	°C	-55 to +175		
Soldering temperature	T _L	°C	260	1.6mm (0.063") from case for 10s	
Mounting torque	T _M	Nm	0.6	M3 screw Maximum of mounting process: 3	

Note: (1) Typical Reference Conditions: V_{GS} = V_{GS_on} PW < 10 μs, Duty cycle < 1%.



■Static Electrical Characteristics (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Gate threshold voltage	$V_{GS(th)}$	V	2.2	3	4	$V_{DS}=V_{GS}$, $I_D=7.4mA$	Fig.4, 10
				2.4		$V_{DS}=V_{GS}$, $I_D=7.4mA$, $T_J=175^\circ C$	
Drain source breakdown voltage	$V_{(BR)DSS}$	V	1200			$V_{GS}=0V$, $I_D=100\mu A$	
Drain source leakage current	I_{DSS}	μA		3	10	$V_{DS}=1200V$, $V_{GS}=0V$	
Gate source leakage current	I_{GSS}	nA		10	100	$V_{GS}=18V$, $V_{DS}=0V$	
Current drain source on-state resistance	$R_{DS\ ON}$	m Ω		45		$V_{GS}=15V$, $I_D=19A$	Fig.5, 6, 7
				36	52	$V_{GS}=18V$, $I_D=19A$	
				68		$V_{GS}=15V$, $I_D=19A$, $T_J=175^\circ C$	
				59		$V_{GS}=18V$, $I_D=19A$, $T_J=175^\circ C$	
Transconductance	g_f	S		18		$V_{DS}=20V$, $I_D=19A$	Fig.4
				17		$V_{DS}=20V$, $I_D=19A$, $T_J=175^\circ C$	

■Dynamic Electrical Characteristics (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Input capacitance	C_{iss}	pF		1981		$V_{DS}=1000V$, $V_{GS}=0V$, $T_J=25^\circ C$, $f=100kHz$, $V_{AC}=25mV$	Fig.13, 14
Output capacitance	C_{oss}			85			
Reverse capacitance	C_{rss}			3.2			
Coss stored energy	E_{oss}	μJ		51			Fig.15
Gate source charge	Q_{gs}	nC		25.5		$V_{DS}=1000V$, $V_{GS}=-5/+18V$, $I_D=19A$	Fig.12
Gate drain charge	Q_{gd}			34.4			
Gate charge	Q_g			90			
Internal gate resistance	R_g	Ω		2.3		$f=1MHz$, $V_{AC}=25mV$	

■Switching Characteristics (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Turn on delay time	$t_{d(on)}$	ns		9.9		$V_{DD}=1000V$, $V_{GS}=-5/+18V$, $I_D=19A$, $R_g=2.4\Omega$, $L=100\mu H$	Fig.21
Rise time	t_r			11.8			
Turn off delay time	$t_{d(off)}$	ns		24			
Fall time	t_f			13.7			



Turn on switching energy	E_{on}	uJ		404		$V_{DD}=1000V, V_{GS}=-5/+18V, I_D=19A,$ $R_g=2.4\Omega, L=100uH$	Fig.19, 20
Turn off switching energy	E_{off}			67			

■Body diode characteristics (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Diode forward voltage	V_{SD}	V		4		$V_{GS}=-5V, I_{SD}=9.5A$	Fig.8
				3		$V_{GS}=-5V, I_{SD}=9.5A, T_j=175^\circ C$	
Continuous diode forward current	I_S	A		46		$V_{GS}=-5V, T_c=25^\circ C$	
Reverse recovery time	t_{rr}	nS		15		$V_R=800V, V_{GS}=-5V, I_D=19A,$ $di/dt=2000A/uS$	
Reverse recovery charge	Q_{rr}	nC		152			
Peak reverse recovery current	I_{rrm}	A		17			

■Thermal Characteristics (Ta=25°C unless otherwise specified)

SYMBOL	PARAMETER	UNIT	Typ.
$R_{\theta J-C}$	Thermal Resistance from Junction to Case	$^\circ C/W$	0.52

■Typical Characteristics

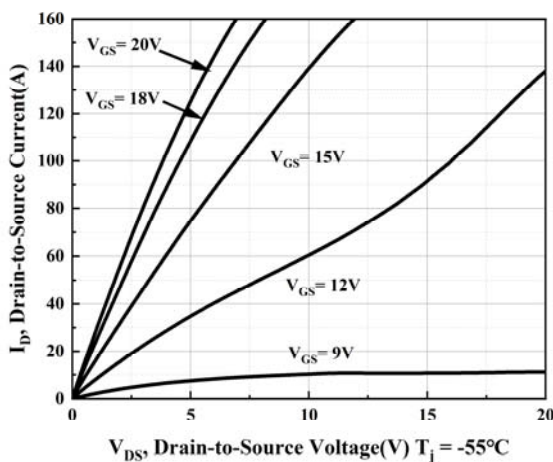


Figure 1. Output Characteristics $T_j = -55^\circ C$

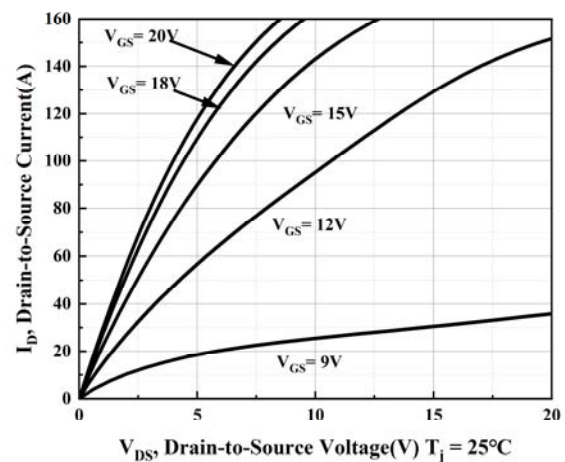


Figure2. Output Characteristics $T_j = 25^\circ C$

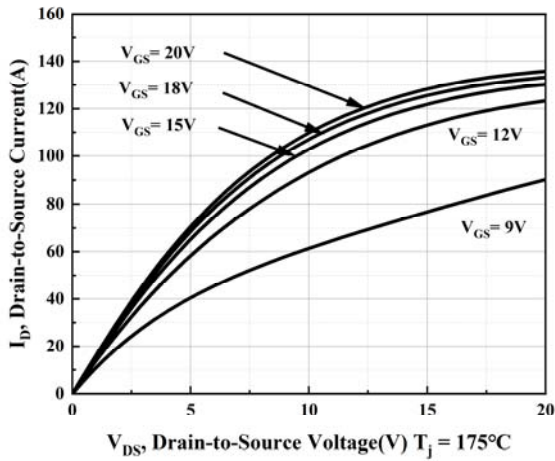


Figure 3. Output Characteristics $T_j = 175^\circ\text{C}$

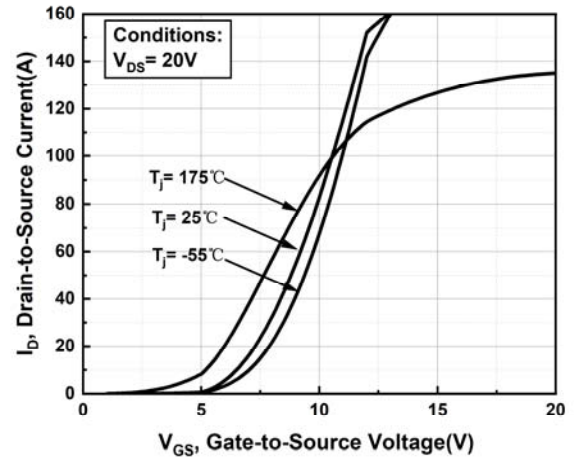


Figure 4. Transfer Characteristics for Various Junction Temperature

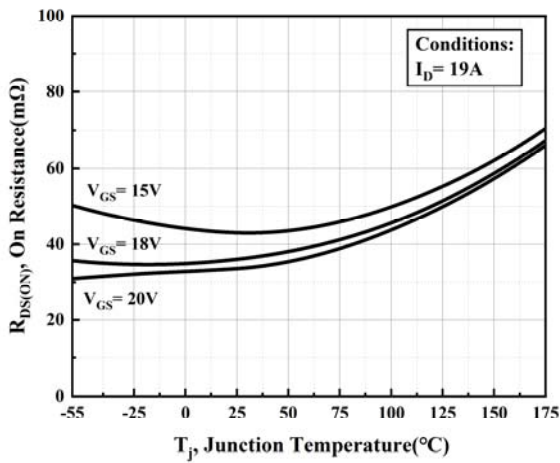


Figure 5. On-resistance vs. Temperature for Various Gate Voltage

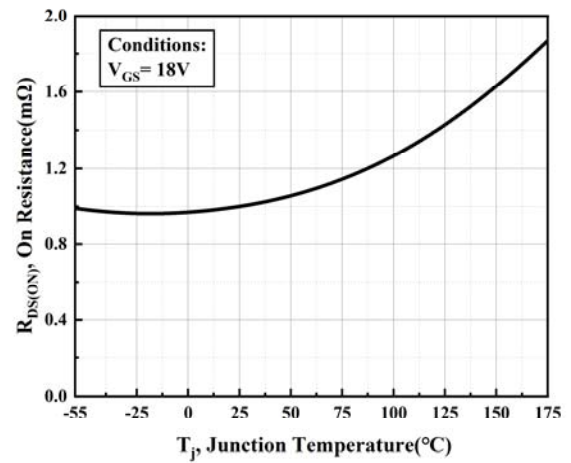


Figure 6. Normalized on-resistance vs. Temperature

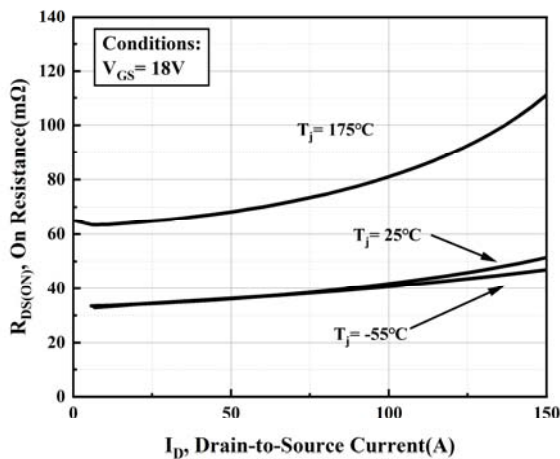


Figure 7. On-resistance vs. Drain Current

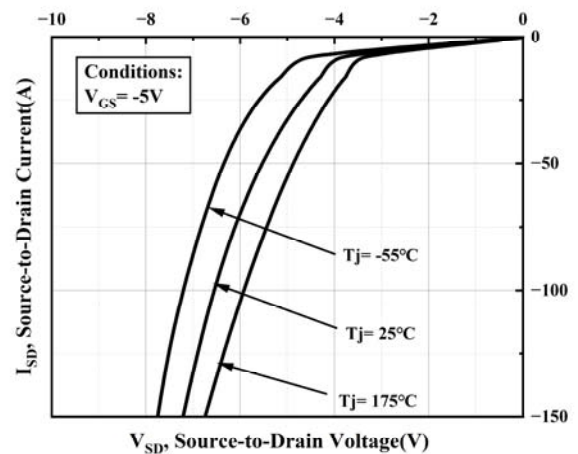


Figure 8. Body Diode Characteristic

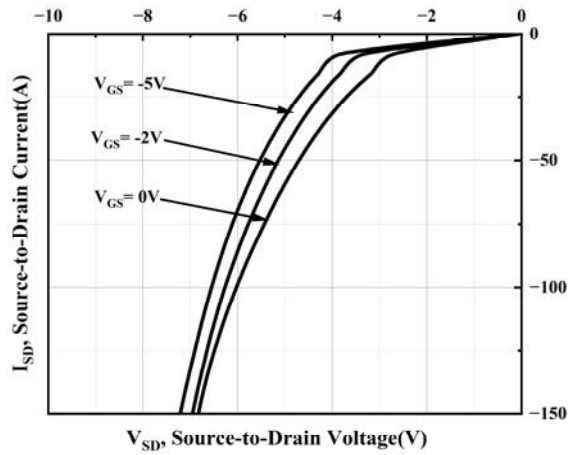


Figure 9. Body Diode Characteristic at $T_j = 25\text{ }^{\circ}\text{C}$

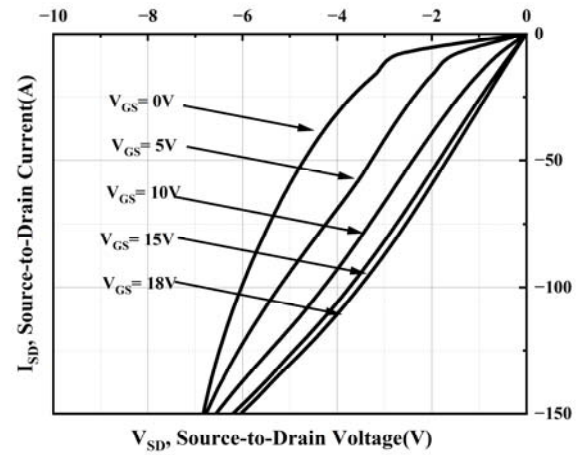


Figure 10. 3rd quadrant Characteristic at $T_j = 25\text{ }^{\circ}\text{C}$

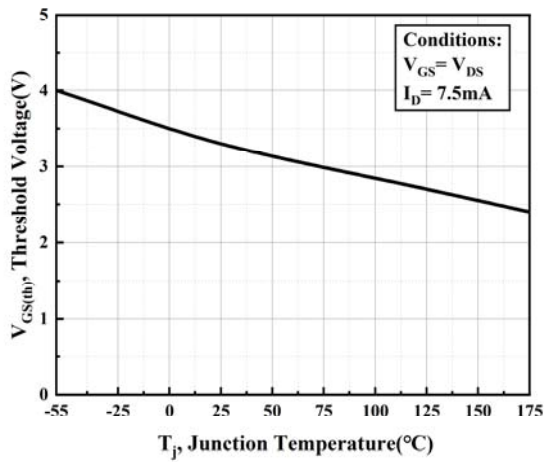


Figure 11. Threshold Voltage vs. Temperature

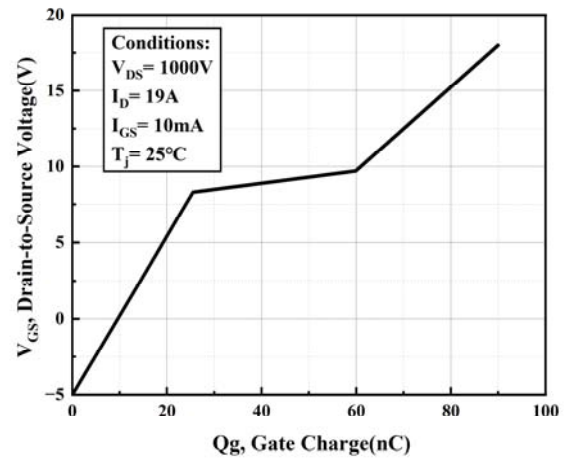


Figure 12. Gate Charge Characteristic Figure

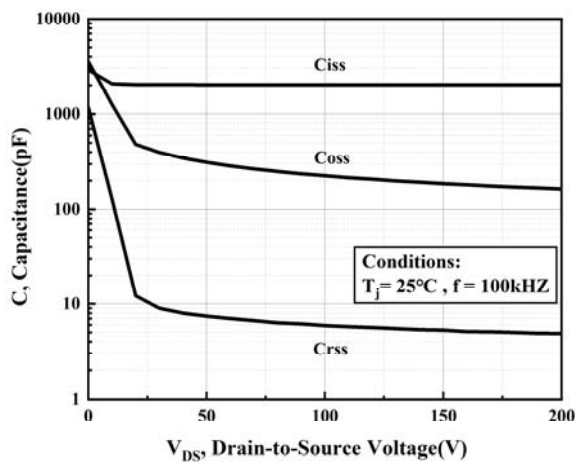


Figure 13. Capacitances vs. Drain Source Voltage (0-200V)

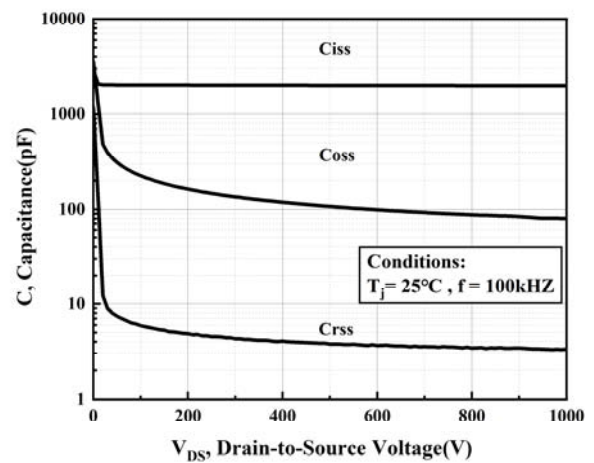


Figure 14. Capacitances vs. Drain Source Voltage (0-1000V)

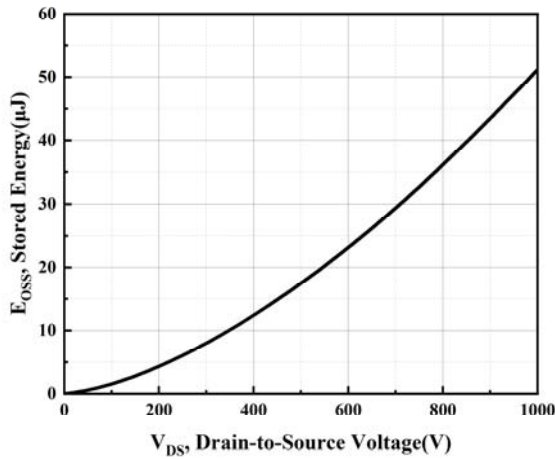


Figure 15. Output Capacitor Stored Energy

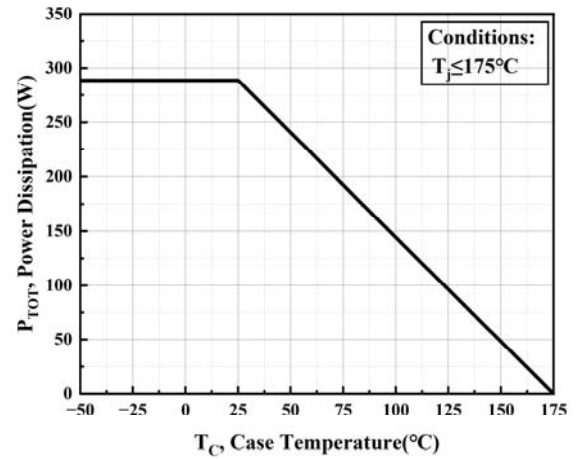


Figure 16. Maximum Power Dissipation Derating vs. Case Temperature

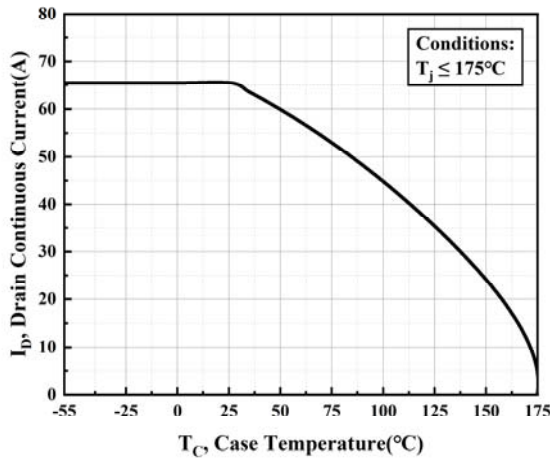


Figure 17. Continuous Drain Current Derating vs. Case Temperature

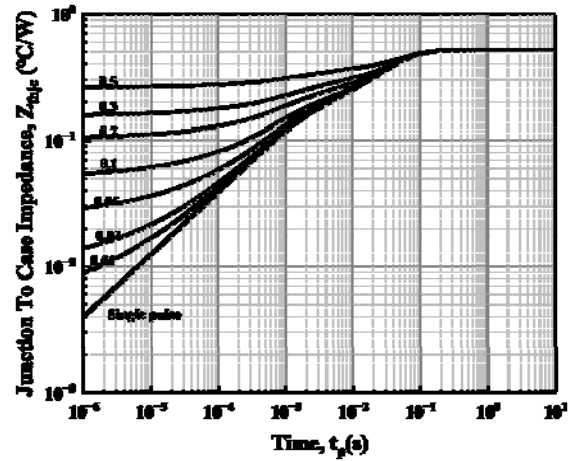


Figure 18. Transient Thermal Impedance (Junction - Case)

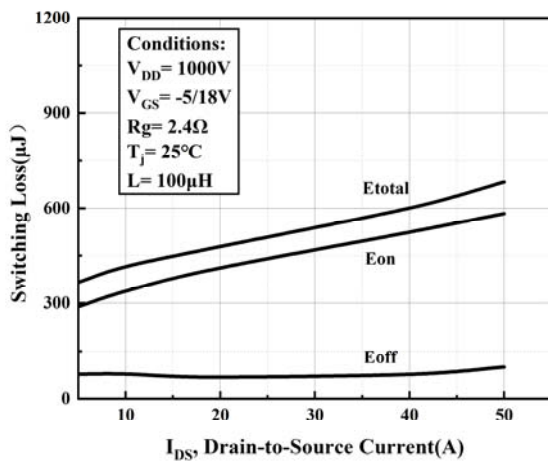


Figure 19. Clamped Inductive Switching Energy vs. Drain Current

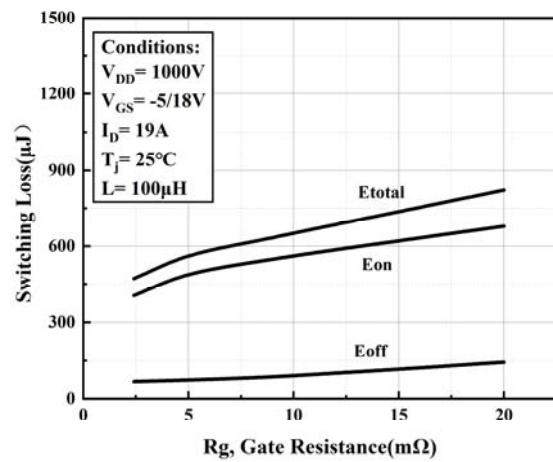


Figure 20. Clamped Inductive Switching Energy vs. R_g

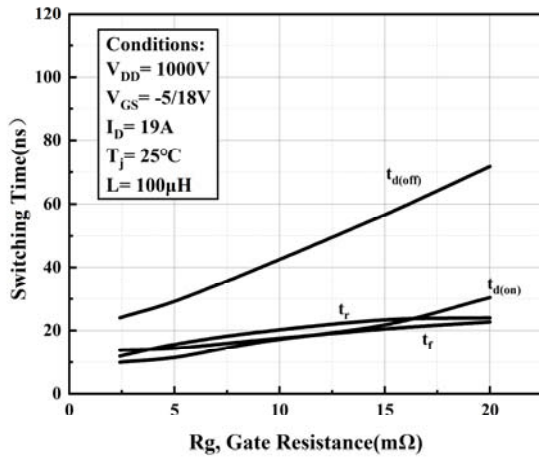


Figure 21. Switching Times vs. R_g

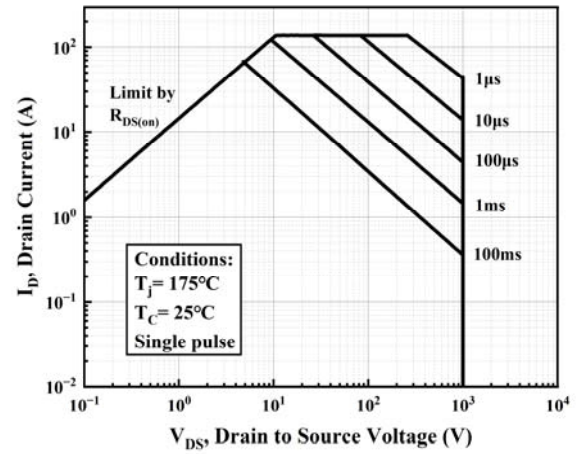


Figure 22. Safe Operating Area

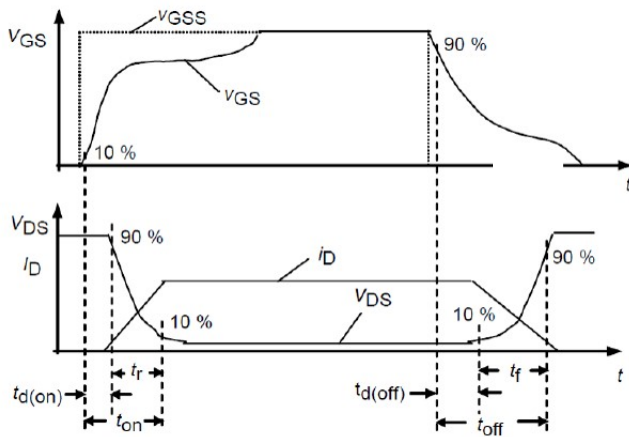


Figure 23. Switching Times Definition

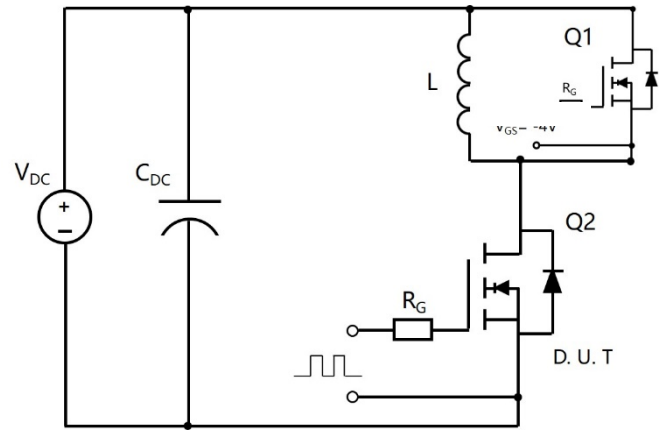
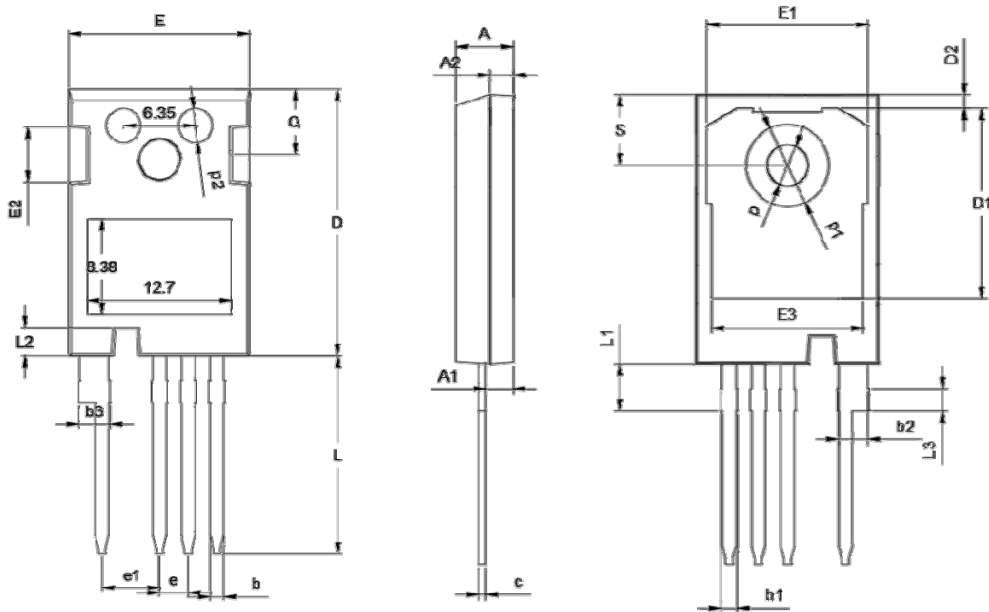


Figure 24. Clamped Inductive Switching Waveform Test Circuit

■Outline Dimensions



TO247-4L			
Dim	Min	Norm	Max
A	4.80	5.00	5.20
A1	2.30	2.40	2.50
A2	1.88	1.98	2.08
b	1.10	1.20	1.30
b1	1.20	/	1.50
b2	2.35	2.55	2.75
b3	2.45	/	2.85
c	0.55	0.60	0.65
D	23.3	23.45	23.6
D1	16.25	16.55	16.85
D2	1.00	/	1.30
e	TYP2.54		
e1	TYP5.06		
E	15.75	15.90	16.05
E1	13.80	/	14.20
E2	4.40	4.75	5.10
E3	13.00	/	13.45
L	17.34	17.49	17.64
L1	4.00	/	4.30
L2	2.35	/	2.65
L3	TYP1.98		
Q	5.60	5.80	6.00
S	6.05	/	6.30
p	TYP3.58		
p1	TYP7.18		
p2	TYP3.00		



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